Lead-Free Solder Paste
PF602-P30

Rev. 2019/01/09 Ver. 03-01

BASIC OVERVIEW

Sn42Bi58 Solder Paste
No Clean
Zero Halogen
Low Melting Point

APPLICATIONS

The Solder Paste is Intended for Industrial Use Only
Low Melting Point Lead-Free SMD Solder Paste
Wide Range of Applications and PCB designs

SPECIFICATION

Appearance	Gray paste w/o visible foreign and clusters		
Alloy Composition	Sn42/Bi58		JIS-Z-3282
Melting Point	139°C		
Particle Size	(Type 3)	20μm - 45μm	J-STD-005
	(Type 4)	20μm - 38μm	
Powder Shape	Spherical		
Flux Content	10 ± 1.0 wt%		JIS-Z-3197
Viscosity	170 ± 50 Pa.s (25±1°C, 10rpm, Malcom)		JIS-Z-3284
Flux Type	ROL0		J-STD-004

ALLOY COMPOSITION

(Sn)	(Bi)	(Ag)	(Cu)	(Ni)	(Pb)	(Sb)	(Cd)	(Au)	(In)	(Al)	(As)	(Fe)	(Zn)
REM.	57.0~ 59.0	0.10 MAX	0.05 MAX	0.01 MAX	0.05 MAX	0.05 MAX	0.002 MAX	0.05 MAX	0.10 MAX	0.001 MAX	0.03 MAX	0.02 MAX	0.001 MAX

(wt%)

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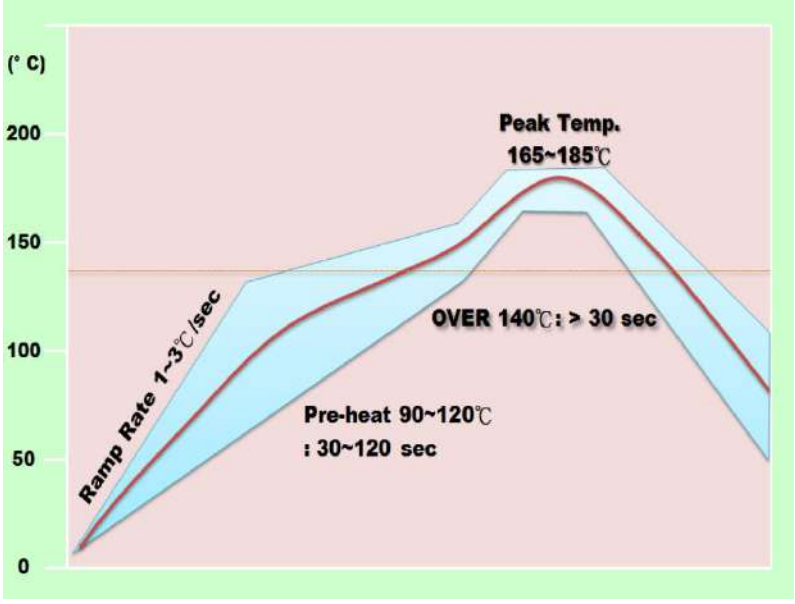
PERFORMANCE & RELIABILITY

Copper Plate Corrosion Test	Pass	IPC-TM-650, 2.6.15
Halogen Content Test	ROL0	BS EN14582
Copper Mirror Test	Pass	IPC-TM-650, 2.3.32
Viscosity Test (25°C,10 rpm)	170 ± 50 Pa.s	JIS-Z-3284
Spreading Test	> 70%	JIS-Z-3197
Slump Test	Pass	JIS-Z-3284

S.I.R. Test ▲	Pass	IPC-TM-650, 2.6.3.7
Electro Migration Test ◆	Pass	IPC-TM-650, 2.6.14.1

▲ *Test Conditions: 40°C, 90% RH for 168hrs* ◆ *Test Conditions: 65°C, 88.5% RH for 596 hrs*

RECOMMENDED REFLOW PROFILE



Ramp Up Rate (30-90°C): **1.0-3.0°C/s**

Pre-heating Time (90-120°C): **30-120s**

Time Period Above 140°C: **> 30s**

Peak Temperature: **165-185°C**

Ramp Down Cooling Rate: **1.0-6.0°C/s**

Note: The recommended reflow profile is provided as a guideline. Optimal profile may differ due to oven type, assembly layout or other process variables.

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STORAGE & HANDLING:

- Refrigerate solder paste at 0-10°C. Shelf life is 6 months from production date (sealed package).
- Keep away from direct sunlight.
- Allow paste to reach ambient temperature (22-28°C) prior to use for 3-4 hrs. Do not heat up solder paste abruptly.
- Well mix paste with plastic spatula for 1min before use (jars packaging).
- It is recommended to finish fresh paste within 24 hrs. To maintain paste quality, make sure not to store used paste and fresh paste in the same jar.
- If printing process was interrupted for more than 1 hr, remove the remained paste from the stencil and seal in the jar.
- Recommended printing environment is 22-28°C and RH 30-60%.
- To clean up printed circuit boards, it is suggested to use ethanol or isopropanol.

Note: For more information, please refer to solder paste application guideline sheet

HOW TO ORDER

PF602 – P30 – T4 – 500

Solder Alloy	Flux	Particle Size	Weight / Packaging
PF602 = Sn42/Bi58	P30 = ROL0	T3 = 20-45µm	30 = syringe 30g
		T4 = 20-38µm	100 = syringe 100g
			150 = syringe 150g
			250 = plastic jar 250g
			500 = plastic jar 500g
			600 = small cartridge 600g
			1200 = large cartridge 1200g

CONTACTS

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